

Two 3M Papers to be Presented at the International Microelectronics and Packaging Society on Embedded Capacitance Materials

3M will present two papers on its embedded capacitor materials at IMAPS 2005, the 38th International Symposium on Microelectronics, held at the Pennsylvania Convention Center, Philadelphia, Penn., Sept. 25 to 29.

The first presentation, "Thin Substrate Flip Chip Assembly - Managing Substrate Warp Through Controlled Thermal Process," will take place Tuesday, Sept. 27, 3:15 p.m. to 4:55 p.m. Shichun Qu, product development specialist, 3M Electronics Markets Materials Division, will present information on 3M multilayer IC substrate technologies, substrate warping challenges and managing warp through control of the thermal process.

A second presentation, "Decoupling of High-Speed Digital Electronics with Embedded Capacitance," will take place Wednesday, Sept. 28, 9:45 a.m. to 11:25 a.m. Joel S. Peiffer, applications engineering specialist, 3M Electronic Solutions Division, will present information on a 3M laminate material that allows designers and manufacturers of high-speed, digital-printed circuit boards to achieve higher speeds while simplifying design trade-offs. When used as a power-ground core in a multilayer printed circuit board, 3M embedded capacitor material effectively becomes a decoupling capacitor inside the board. The material allows designers to eliminate large numbers of decoupling capacitors, increasing useable board area; enables faster signaling; lowers radiated emissions (EMI); and saves engineering time associated with power distribution design and board layout. Printed circuit board fabricators can use the material in military, automated test equipment, computer and telecommunications applications.

For more information about 3M brand embedded capacitor material, visit www.3M.com/imaps.

About 3M Electronics

3M Electronics, co-located in Austin, Texas, and St. Paul, Minn., has numerous technologies and provides a wide range of products for the electronics market. The business provides products and solutions to meet the electronic industry's challenges of protecting sensitive components and precisely delivering them to the assembly point, such as carrier and cover tapes and trays, as well as flexible and multilayer microinterconnect packaging solutions; embedded capacitor materials; copper and fiber interconnect systems; cables and cable assemblies; static control products, Textool brand test and burn-in sockets; tapes, abrasives, chemicals and materials, and ceramic textiles and composites.

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